

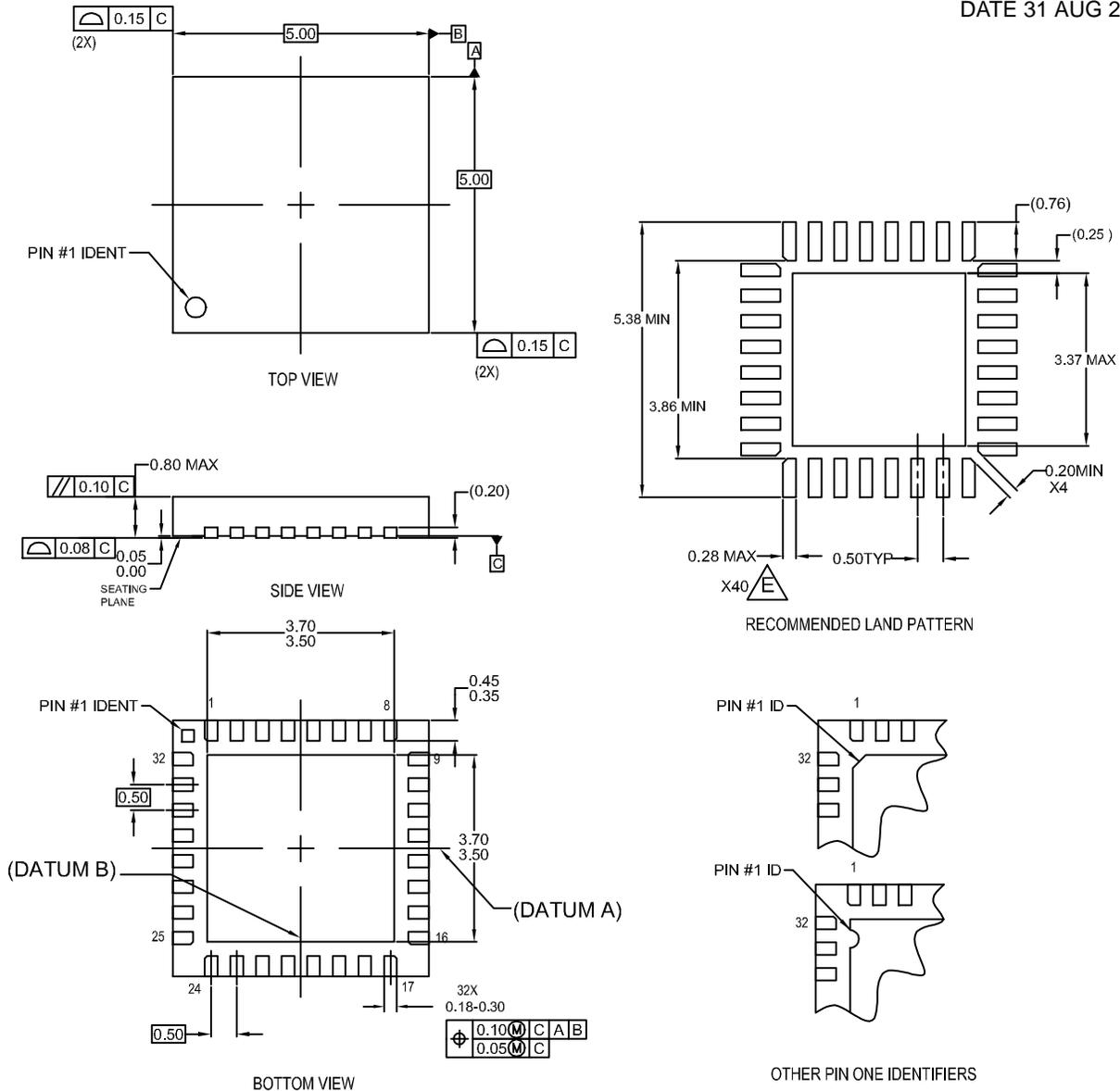
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



WQFN32 5x5, 0.5P CASE 510BU ISSUE O

DATE 31 AUG 2016



NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-220, VARIATION WHHD-4. THIS PACKAGE IS ALSO FOOTPRINT COMPATIBLE WITH WHHD-5.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
- D. LAND PATTERN PER IPC SM-782.
- E. WIDTH REDUCED TO AVOID SOLDER BRIDGING.
- F. DIMENSIONS ARE NOT INCLUSIVE OF BURRS, MOLD FLASH, OR TIE BAR PROTRUSIONS.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WQFN32 5X5, 0.5P	PAGE 1 OF 2

